L Number	Hits	Search Text	DB	Time stamp
1.	22783	((conducitve adj paste) or paste or (paste adj material)) same advan\$4	USPAT; EPO; JPO;	2003/12/14 18:14
			DERWENT; USOCR	
3	2103	(((conducitve adj paste) or paste or (paste adj material))	USPAT;	2003/12/14 17:56
		same advan\$4) and (carrier or (carrier adj board))	EPO; JPO; DERWENT;	
	1227		USOCR	
	1227	((((conducitve adj paste) or paste or (paste adj material)) same advan\$4) and (carrier or (carrier adj board))) and	USPAT; EPO; JPO;	2003/12/14 17:56
		(component or die or chip or IC)	DERWENT;	
4	131	(((((conducitve adj paste) or paste or (paste adj	USOCR	2002/40/44 47.57
5	101	material)) same advan\$4) and (carrier or (carrier adj	USPAT; EPO; JPO;	2003/12/14 17:57
		board))) and (component or die or chip or IC)) and (PCB	DERWENT;	
	119	or (circuit adj board)) ((((((conducitve adj paste) or paste or (paste adj	USOCR	0000/40/4440.44
	119	material)) same advan\$4) and (carrier or (carrier adj	USPAT; EPO; JPO;	2003/12/14 18:14
		board))) and (component or die or chip or IC)) and (PCB	DERWENT;	
		or (circuit adj board))) and (solder or (solder adj ball) or (solder adj bump))	USOCR	
6	41	(((((((conducitve adj paste) or paste or (paste adj	USPAT;	2003/12/14 18:15
		material)) same advan\$4) and (carrier or (carrier adj	EPO; JPO;	
		board))) and (component or die or chip or IC)) and (PCB or (circuit adj board))) and (solder or (solder adj ball) or	DERWENT;	
		(solder adj bump))) and (melting adj point)	USOCR	
7	1346	174/250-268.ccls. and ((conducitve adj paste) or paste	USPAT;	2003/12/14 18:14
		or (paste adj material))	EPO; JPO;	
			DERWENT; USOCR	
8	930	(174/250-268.ccls. and ((conducitve adj paste) or paste	USPAT;	2003/12/14 18:14
		or (paste adj material))) and (solder or (solder adj ball) or (solder adj bump))	EPO; JPO;	
		or (solder adj bump))	DERWENT; USOCR	
9	244	((174/250-268.ccls. and ((conducitve adj paste) or paste	USPAT;	2003/12/14 18:33
		or (paste adj material))) and (solder or (solder adj ball) or (solder adj bump))) and (melting adj point)	EPO; JPO;	
		or (solder adj bump))) and (merung adj point)	DERWENT; USOCR	
10	230	paste same (high\$3 adj melting adj point) same solder	USPAT;	2003/12/14 18:35
			EPO; JPO; DERWENT;	•
			USOCR	
11	26	361/\$.ccls. and (paste same (high\$3 adj melting adj	USPAT;	2003/12/14 18:39
		point) same solder)	EPO; JPO; DERWENT;	
			USOCR	
12	0	174/250-268/\$.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:40
		adj point) same solder)	EPO; JPO; DERWENT;	
			USOCR	
13	0	257/600-800/\$.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:40
		adj point) same solder)	EPO; JPO; DERWENT;	
			USOCR	
15	21	174/250-268.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:42
		adj point) same solder)	EPO; JPO; DERWENT;	
	i		USOCR	
14	45	257/600-780.ccls. and (paste same (high\$3 adj melting	USPAT;	2003/12/14 18:42
		adj point) same solder)	EPO; JPO; DERWENT;	
			USOCR	